

B-1-2 Determination of Localized State Density Distribution in Glow Discharge Amorphous Silicon

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Introduction Spear and Le Comber have recently succeeded in the reproducible control of n- or p-type conductivity of glow discharge amorphous silicon (GD a-Si) by substitutional doping of phosphorus or boron impurities¹. Consequently, many studies for application of GD a-Si to low-cost solar cells are in progress². Detailed knowledge on electronic density of states in the mobility gap of GD a-Si is now required to improve the efficiency of the photovoltaic cells.

This paper describes a new method to determine gap state density distribution in GD a-Si from the analysis of capacitance-voltage (C-V) characteristics for metallic gate/oxide/GD a-Si (MOS) structures.

Theoretical The surface potential u^a and the space charge capacitance C^a of an a-Si MOS structure are deduced from the C-V curve. Then the density distribution of gap states $N(E)$ is calculated by the equation³

$$N(E) = N(E_F^a + eu^a) = [\partial/\partial(eu^a)] \{ [\int_0^{u^a} C^a(u^a) du^a / \epsilon^a] [C^a(u^a)/e] \}. \quad (1)$$

Here, E_F^a is the Fermi level of a-Si, ϵ^a its dielectric constant and e the electronic charge. In eq. (1) it is assumed that the thermal-release time τ for majority carriers trapped by localized states at E_F^a in the space charge layer is short enough compared with the inverse of measuring frequency τ_m .

Experimental Amorphous Si films were deposited on $\text{SiO}_2/\text{n}^+\text{-Si}(100)$ substrates kept at 300°C by rf glow discharge of $\text{SiH}_4\text{-PH}_3$ or $\text{SiH}_4\text{-B}_2\text{H}_6$ gaseous mixture. A sketch of a fabricated MOS structure is shown in Fig. 1. The C-V curves of MOS diodes measured at 20 Hz are shown in Fig. 2. The relation $\tau \ll \tau_m$ is well satisfied over weak depletion to accumulation condition, by raising the ambient temperature up to 58°C for an n-type specimen (doped 3 ppm PH_3 , $E_C - E_F^a = 0.55$ eV) and up to 97°C for a p-type one (300 ppm B_2H_6 , $E_F^a - E_V = 0.65$ eV). The flat-band voltage V_{FB} for the each specimen was reasonably obtained from a gate voltage above which field induced current through the electrodes A and B (see Fig. 1) sharply increases owing to majority carrier accumulation at the surface. Figure 3 represents the calculated density of localized states for the specimens indicated in

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Fig. 2. This density of states distribution is considerably different from that measured by field effect (F-E) method⁴ which exhibited two peaks of gap state density of the order of 10^{18} - 10^{19} $\text{cm}^{-3}\text{eV}^{-1}$ at 0.4 eV below and above the extended states. In case of the F-E method the surface potential u^a is evaluated by supposing that the surface band bending of a-Si is parabolic. Of course this is a zero order approximation. In contrast to this, the C-V method presented here gives exact u^a as a result of numerical integration of the C-V curve. We found that estimated values of u^a by the F-E method are 30 - 40 % smaller than those by the C-V method. This discrepancy implies that the peak density of gap states suggested by the F-E method arises from the rough evaluation of the surface potential. Surface states at the $\text{SiO}_2/\text{GD a-Si}$ interface, if exist, may give rise to the MOS capacitance, but the influence on the C-V curve is estimated to be negligible even for the surface state density of high 10^{12} $\text{cm}^{-2}\text{eV}^{-1}$.

Conclusion The C-V method can provide a quantitative information on localized states in GD a-Si, being very useful to find optimum conditions for producing the efficient photovoltaic cells, in connection with doping concentration, substrate temperature, discharge kinetics and so on.

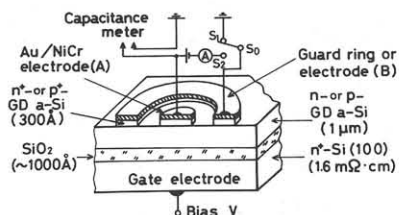


Fig. 1. Schematic of a GD a-Si MOS structure. The connection S_0-S_1 is used for the C-V method and S_0-S_2 for the F-E method.

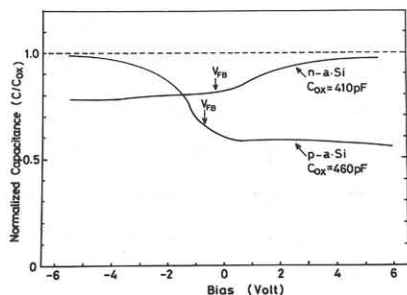


Fig. 2. C-V curves for doped a-Si MOS structure.

- References** (1) W.E. Spear and P.G. Le Comber: Phil. Mag. 33 (1976) 935. (2) D.E. Carlson, C.R. Wronski, J.I. Pankove, P.J. Zanzucchi and D.L. Staebler: RCA Rev. 38 (1977) 211. (3) G.H. Doehler and M. Hirose: Proc. of the 7th Intern. Conf. on Amorphous and Liquid Semiconductors (Edinburg, 1977) p.372. (4) A. Madan and Le Comber: ibid. p.377.

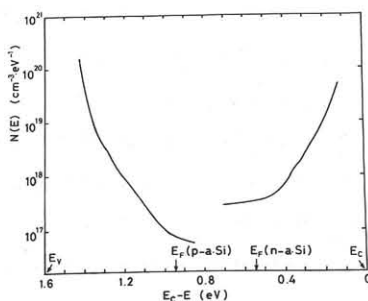


Fig. 3. Density of states distribution in doped GD a-Si.